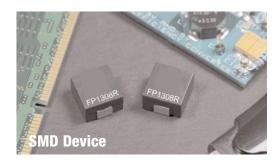
FP1308R

High frequency, high current power inductors



Product features

- 13.4 x 12.7 x 8.0mm surface mount package
- Ferrite core material
- High current carrying capacity, Low core losses
- · Controlled DCR tolerance for sensing circuits
- Inductance range from 110nH to 440nH
- Current range from 37 to 120 Amps
- Frequency range up to 2MHz

Applications

- Multi-phase regulators
- Voltage Regulator Module (VRM)
- Desktop and server VRMs and EVRDs
- Data networking and storage systems
- Graphics cards and battery power systems
- · Point-of-load modules
- DCR sensing

Environmental data

- Storage temperature range (component): -40 °C to +125 °C
- Operating temperature range: -40 °C to +125 °C (ambient plus self-temperature rise)
- Solder reflow temperature:
 J-STD-020 (latest revision) compliant









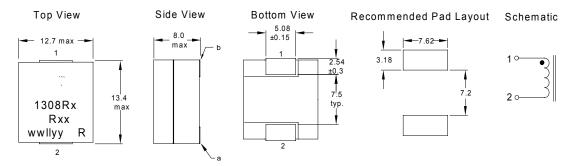
Product Specifications							
Part	OCĽ	FLL ²	I _{rms} ³	I _{sat} 1⁴	I _{sat} 2⁵	DCR (mΩ)	
Number	± 10% (nH)	(nH)	(Amps)	@ 25°C (Amps)	@ 125°C (Amps)	@ 20°C	K-factor
R1 Version							
FP1308R1-R11-R	110	79		120	105		233
FP1308R1-R21-R	210	152		80	68		233
FP1308R1-R26-R	260	187	57	64	52	0.32 ± 9.4%	233
FP1308R1-R32-R	320	230		52	40		233
FP1308R1-R44-R	440	317		37	28		233
R2 Version							
FP1308R2-R11-R	110	79		120	105		233
FP1308R2-R21-R	210	152		80	68		233
FP1308R2-R26-R	260	187	45	64	52	0.53 ± 10%	233
FP1308R2-R32-R	320	230		52	40		233
FP1308R2-R44-R	440	317		37	28		233
R3 Version							
FP1308R3-R11-R	110	79		120	105		233
FP1308R3-R21-R	210	152]	80	68		233
FP1308R3-R26-R	260	187	68	64	52	0.18 ± 20%	233
FP1308R3-R32-R	320	230		52	40		233
FP1308R3-R44-R	440	317]	37	28		233

¹ Open Circuit Inductance (OCL) Test Parameters: 100kHz, 1.0 V_{rms} , 0.0Adc

necessary for AC currents. PCB pad layout, trace thickness and width, air-flow and proximity of other heat generating components will affect the temperature rise. It is recommended the part temperature not exceed 125°C under worst case operating conditions verified in the end application.

- 5 Isat2: Peak current for approximately 20% rolloff at +125°C.
- 6 K-factor: Used to determine B_{p-p} for core loss (see graph). $B_{p-p} = K \cdot L \cdot \Delta I \cdot 10^{-3}$, B_{p-p} (Gauss), K: (K-factor from table), L: (inductance in nH), ΔI (peak-to-peak ripple current in amps).
- 7 Part Number Definition: FP1308Rx-Rxx-R
 - FP1308 = Product code and size
 - Rx = DCR indicator
- Rxx = Inductance value in μ H, R = decimal point.
- "-R" suffix = RoHS compliant

Dimensions- mm

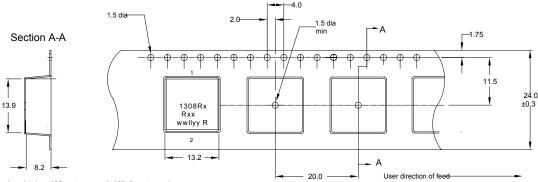


The nominal DCR is measured from point "a" to point "b"

All soldering surfaces to be coplanar within 0.1016mm.

 $Part\ Marking:\ FP1308R\ (Rx=DRC\ indicator) \qquad Rxx=Inductance\ value\ in\ \mu H.\ (R=Decimal\ point). \qquad wwllyy=Date\ code \qquad \qquad R=Revision\ level$

Packaging information - mm



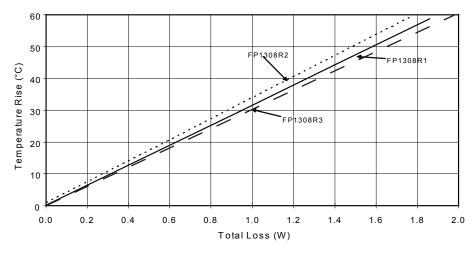
Supplied in tape-and-reel packaging, 400 parts per reel, 13" diameter reel.

² Full Load Inductance (FLL) Test Parameters: 100kHz, 1.0V_{rms}, I_{sat}1.

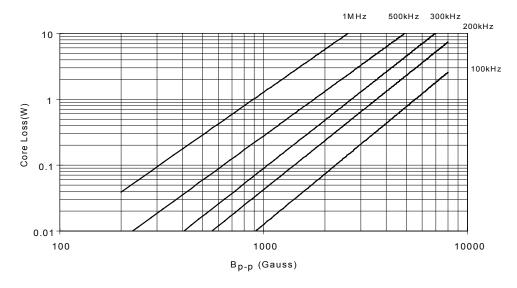
³ I_{rms}: DC current for an approximate temperature rise of 40°C without core loss. Derating is

⁴ $\,$ I_{Sat}: Peak current for approximately 20% rolloff at +25°C.

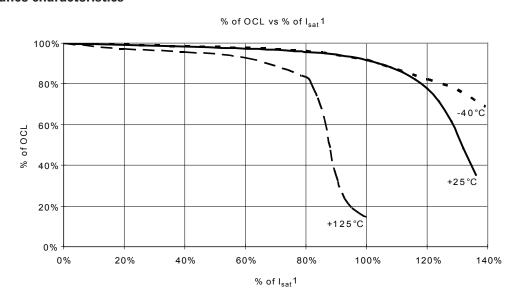
Temperature rise vs total loss



Core loss vs Bp-p



Inductance characteristics



Solder Reflow Profile

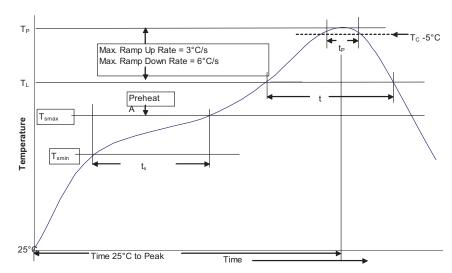


Table 1 - Standard SnPb Solder (T_c)

	Volume	Volume
Package	mm³	mm³
Thickness	<350	≥350
<2.5mm	235°C	220°C
≥2.5mm	220°C	220°C

Table 2 - Lead (Pb) Free Solder (Tc)

Package	Volume mm³	Volume mm³	Volume mm³
Thickness	<350	350 - 2000	>2000
<1.6mm	260°C	260°C	260°C
1.6 - 2.5mm	260°C	250°C	245°C
>2.5mm	250°C	245°C	245°C

Reference JDEC J-STD-020

Profile Feature		Standard SnPb Solder	Lead (Pb) Free Solder	
Preheat and Soak	• Temperature min. (T _{smin})	100°C	150°C	
	Temperature max. (T _{smax})	150°C	200°C	
	• Time (T _{smin} to T _{smax}) (t _s)	60-120 Seconds	60-120 Seconds	
Average ramp up rate T _{Smax} to T _p		3°C/ Second Max.	3°C/ Second Max.	
Liquidous temperature (TL)		183°C	217°C	
Time at liquidous (t _L)		60-150 Seconds	60-150 Seconds	
Peak package body temperature (Tp)*		Table 1	Table 2	
Time $(t_p)^{**}$ within 5 °C of the specified classification temperature (T_c)		20 Seconds**	30 Seconds**	
Average ramp-down rate (T _p to T _{smax})		6°C/ Second Max.	6°C/ Second Max.	
Time 25°C to Peak Temperature		6 Minutes Max.	8 Minutes Max.	

 $^{^{\}star}$ Tolerance for peak profile temperature (Tp) is defined as a supplier minimum and a user maximum.

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Eaton Electronics Division 1000 Eaton Boulevard Cleveland, OH 44122

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^{**} Tolerance for time at peak profile temperature (t_p) is defined as a supplier minimum and a user maximum.

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